

PSI Roadshow in Q1,2024

5 Mar. 2024

Safe Harbor Notice

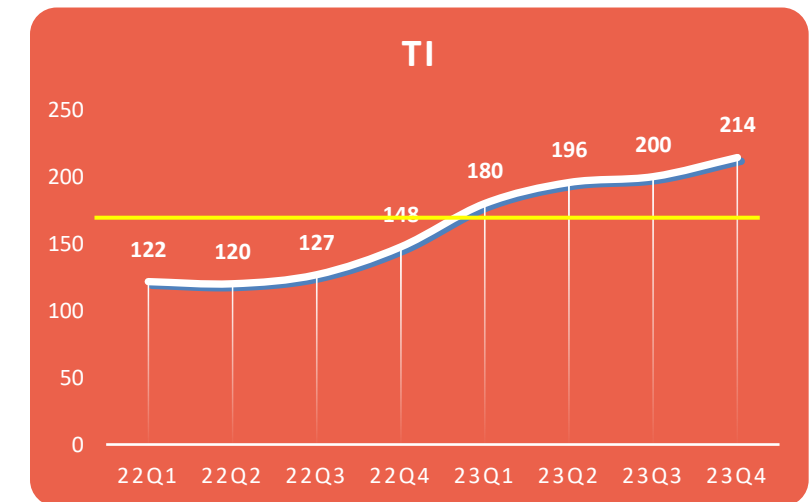
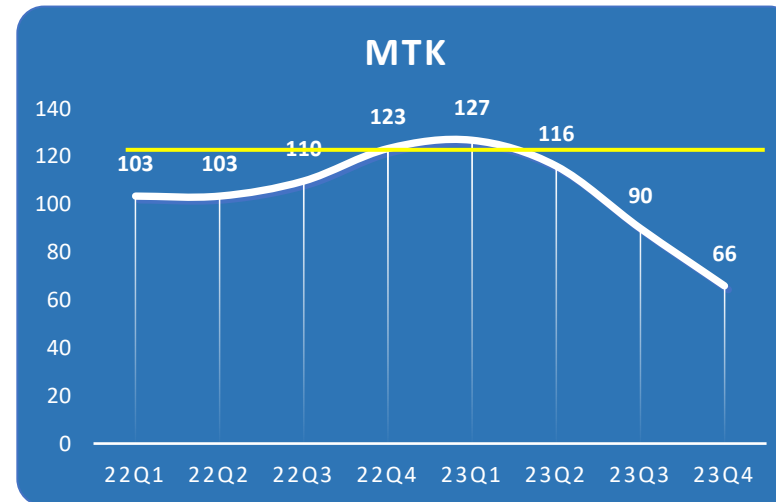
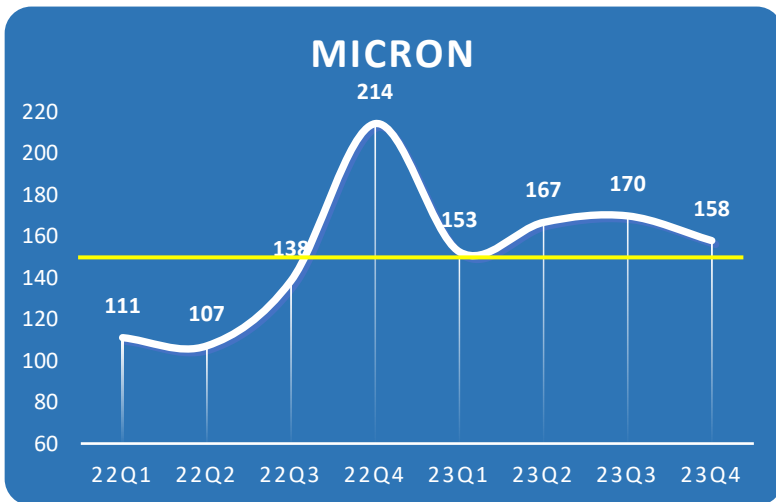
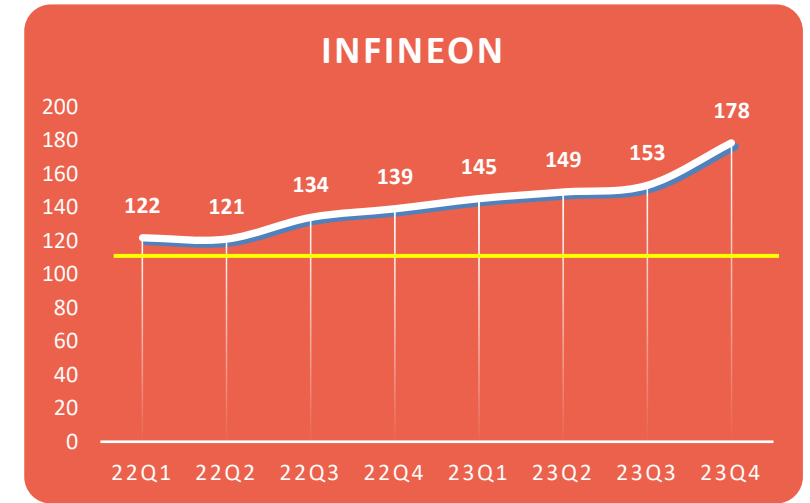
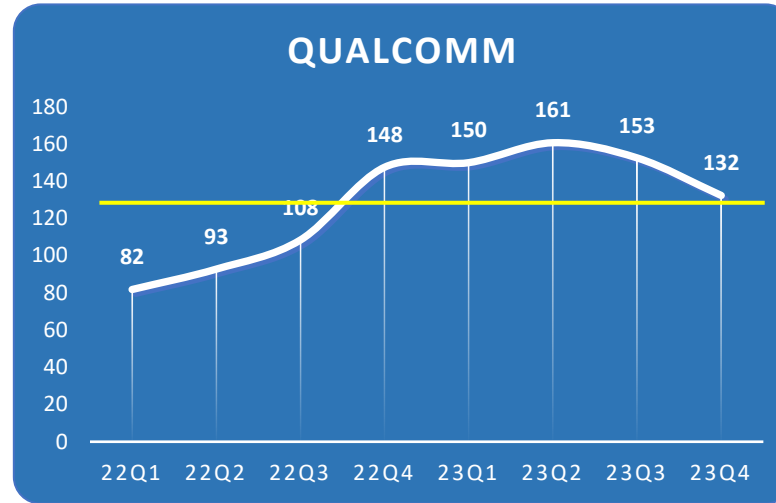
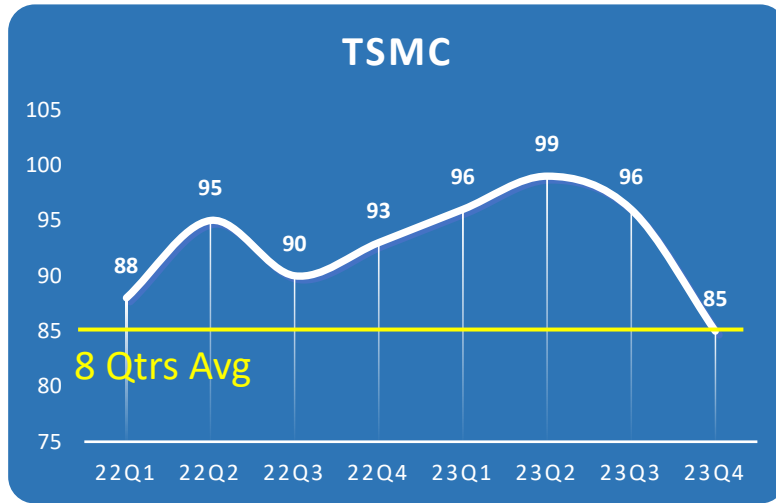
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- The numbers of the presentation are prepared under IFRS.

Agenda

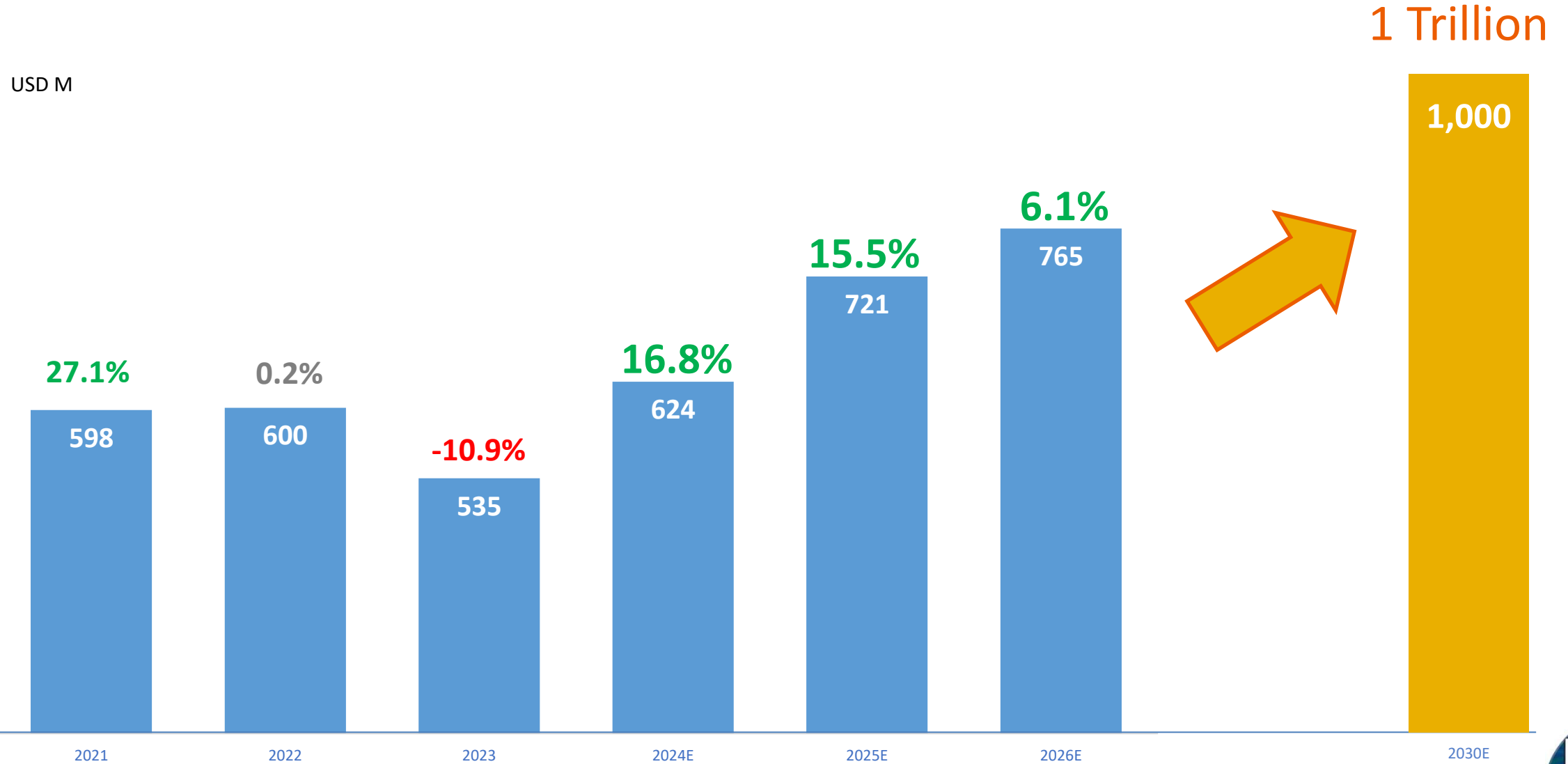
- Semi industry trending
- PSI strategies update
- ESG subject update
- Key takeaways

Semi Outlook

Inventory Show Improvement - Except Power Semi



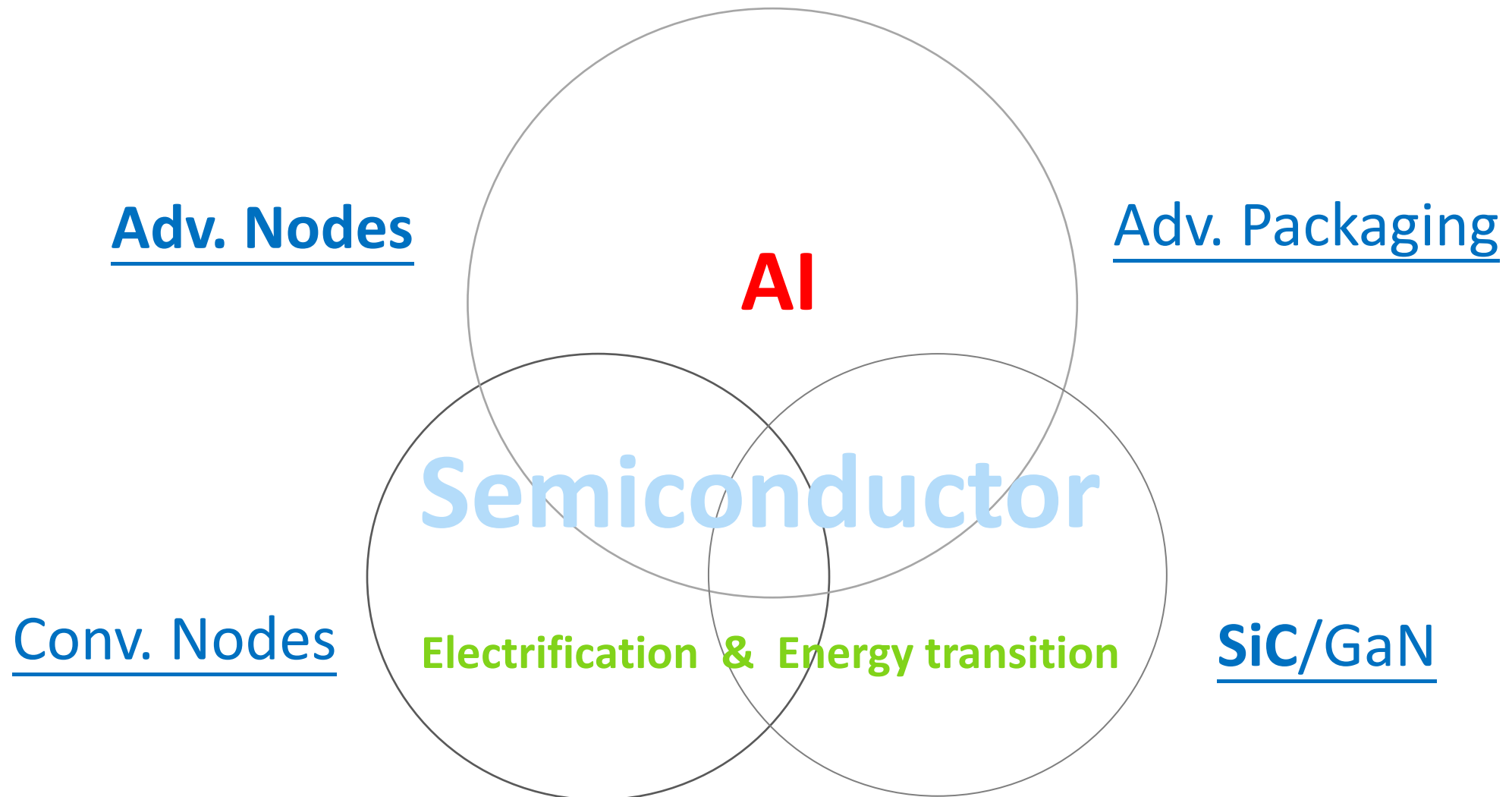
Semi Industry FCST



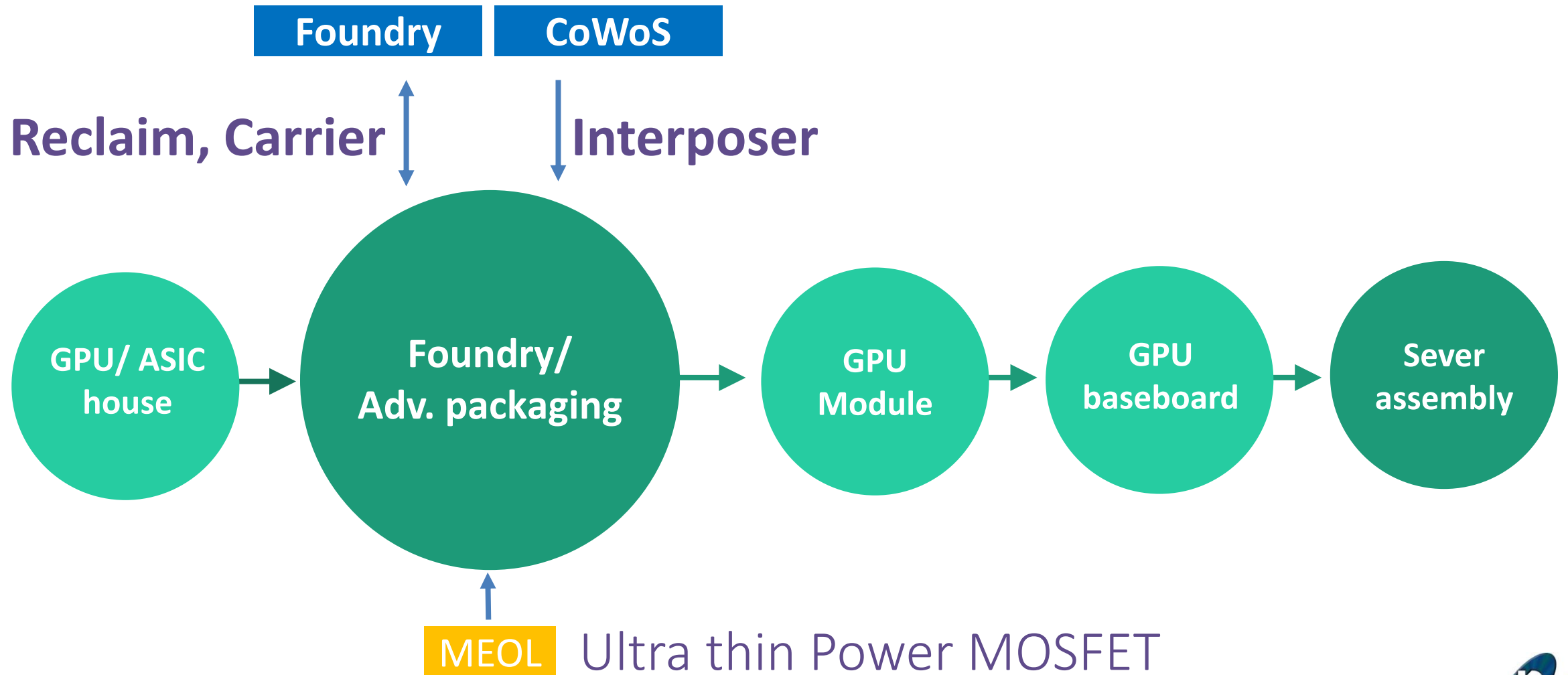
Source: Gartner, PSI estimate



Semiconductor Major Drivers



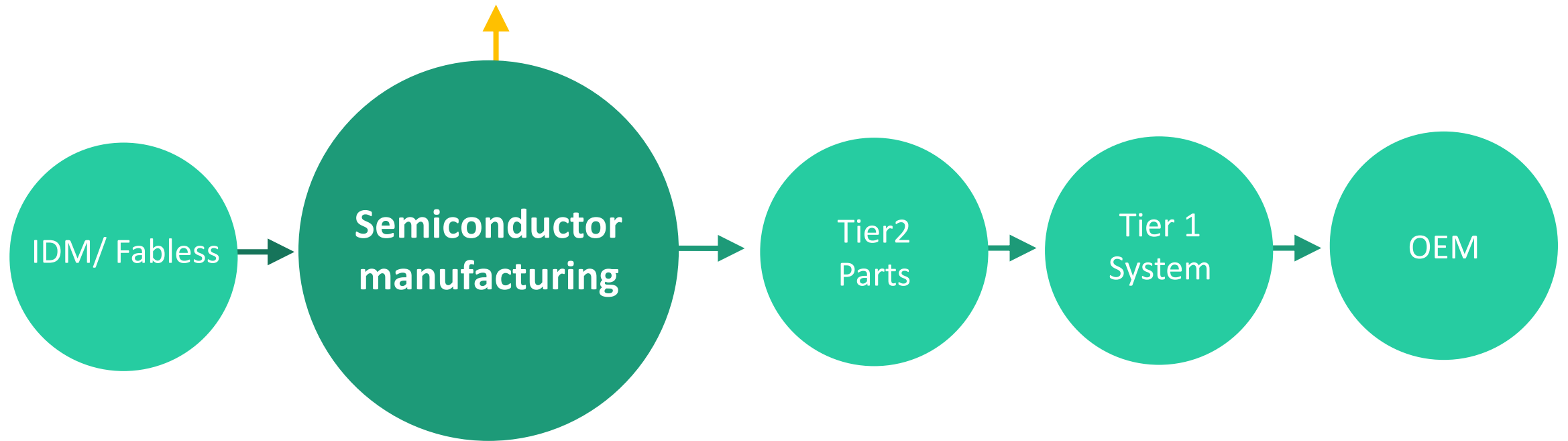
PSI Part Of AI Supply Chain



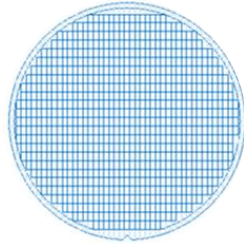
PSI Part Of EV Supply Chain

ATV Grade Si/ SiC Power MOSFET
thinning process

FEOL MEOL BEOL



PSI Key Strategy



- Leading Tech in Ultra clean reclaim wafer
- Tailor made TEST/ CARRIER wafer
- WW No.1 Wafering capacity

- Focus on AI, high power application
- Enabling 8" SiC thinning business
- WW No.1 Thinning Capacity

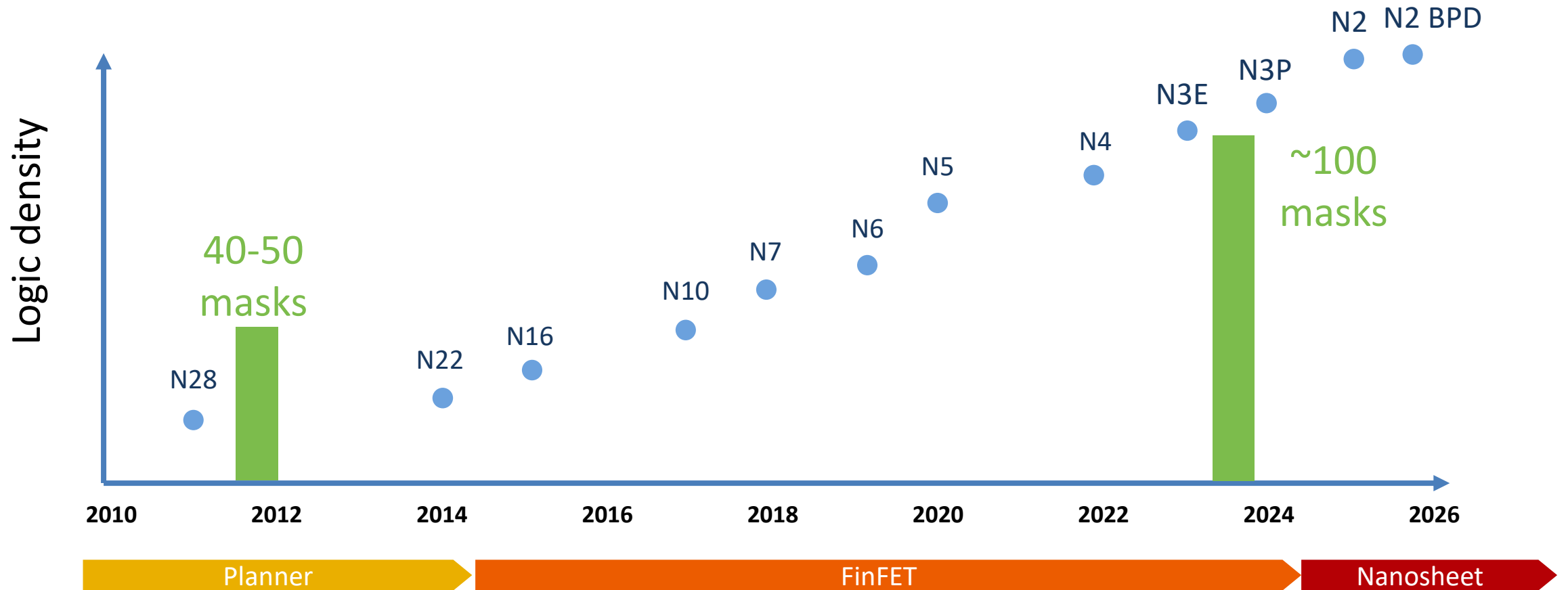


Wafering Business Line

Reclaim demand up driven by Advanced node

Test wafer for carrier wafers emerging in Advanced packaging

Requiring More Advanced Process

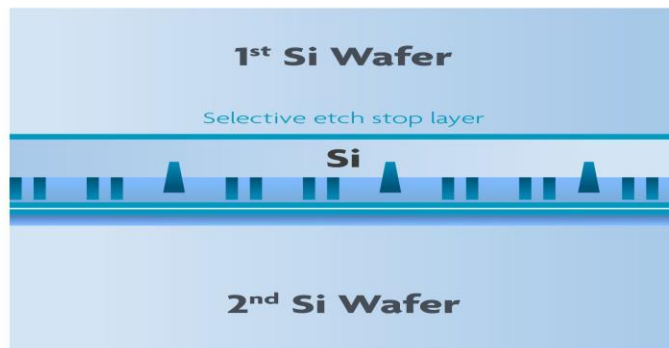


Source: Company data, PSI

Permanent Bonding With Carrier Wafer

BPD
2nm/18A

STEP 2



Permanent bonding
to second Si wafer



Wafer grinding
and **thinning** to $< 5\mu\text{m}$

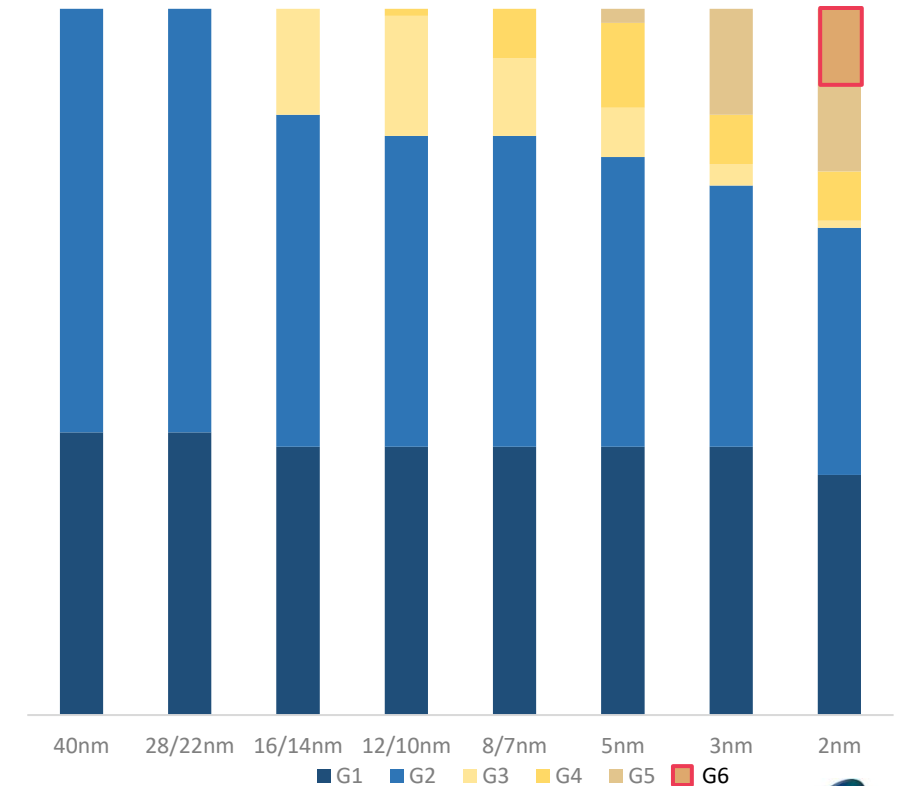
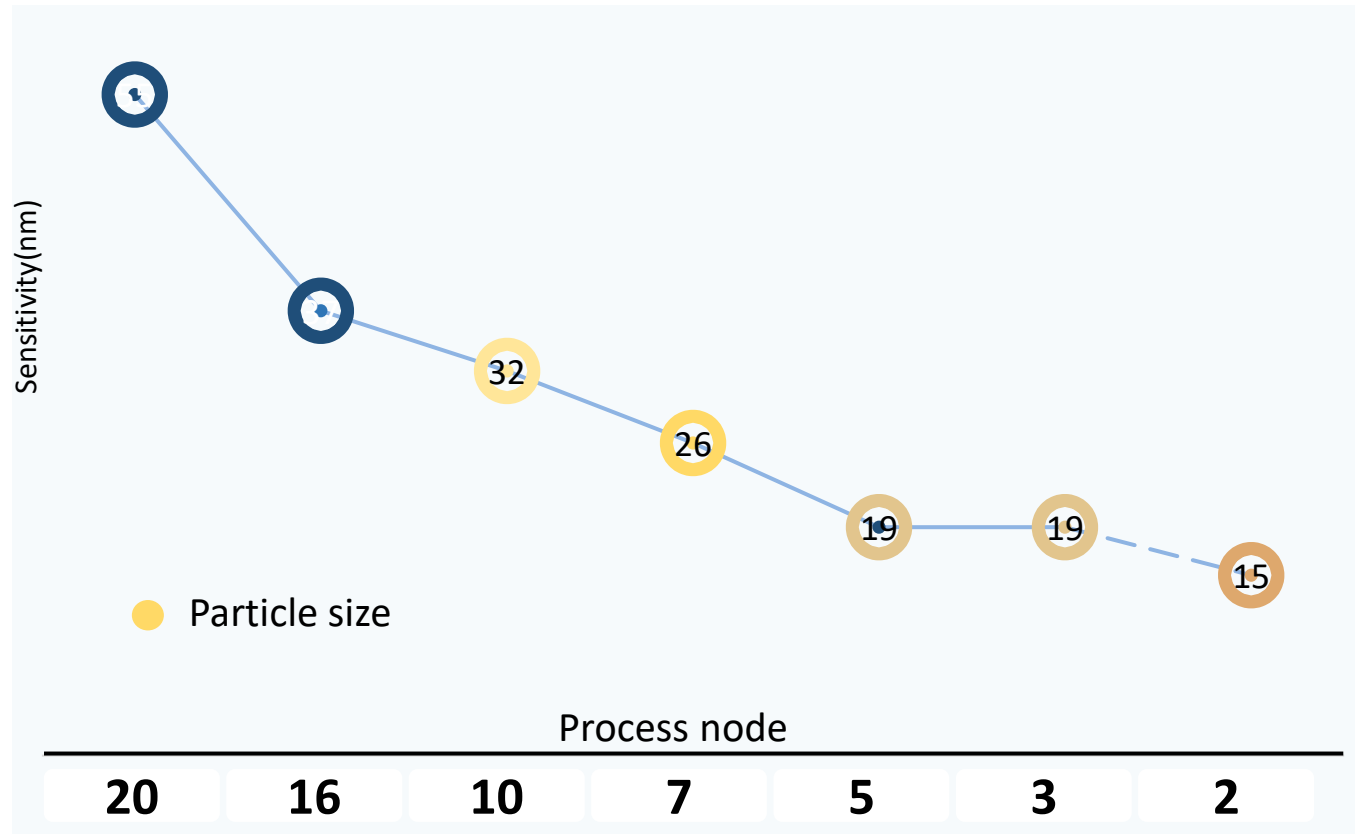


Selective Si etch and
removal of the **buffer layer**

Consuming More high-Grade Reclaim Wafer

2013 2015 2017 2018 2020 2022 2025

High Grade > 25%



Source: KLA, PSI

WW No.1 Lights out Wafering Fab

100

2021

40

2023

15

2025

5

2027



WW No.1 Wafering House Capacity

12

2023

20

2025

30

2027

+60

Tbd building 2



Strategic Expansion in Customers and MFG

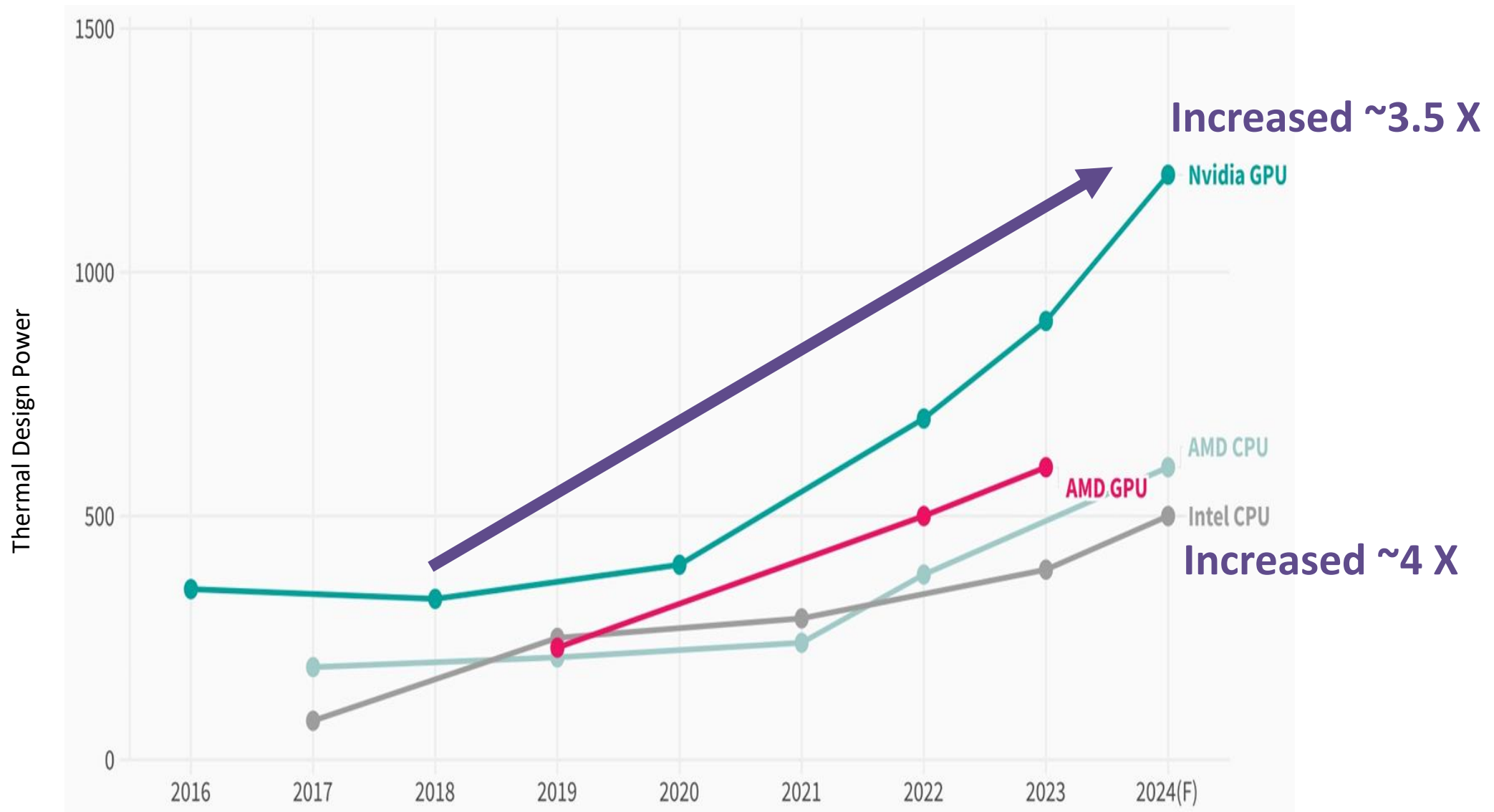


Thinning Business Line

Focus on AI Centric

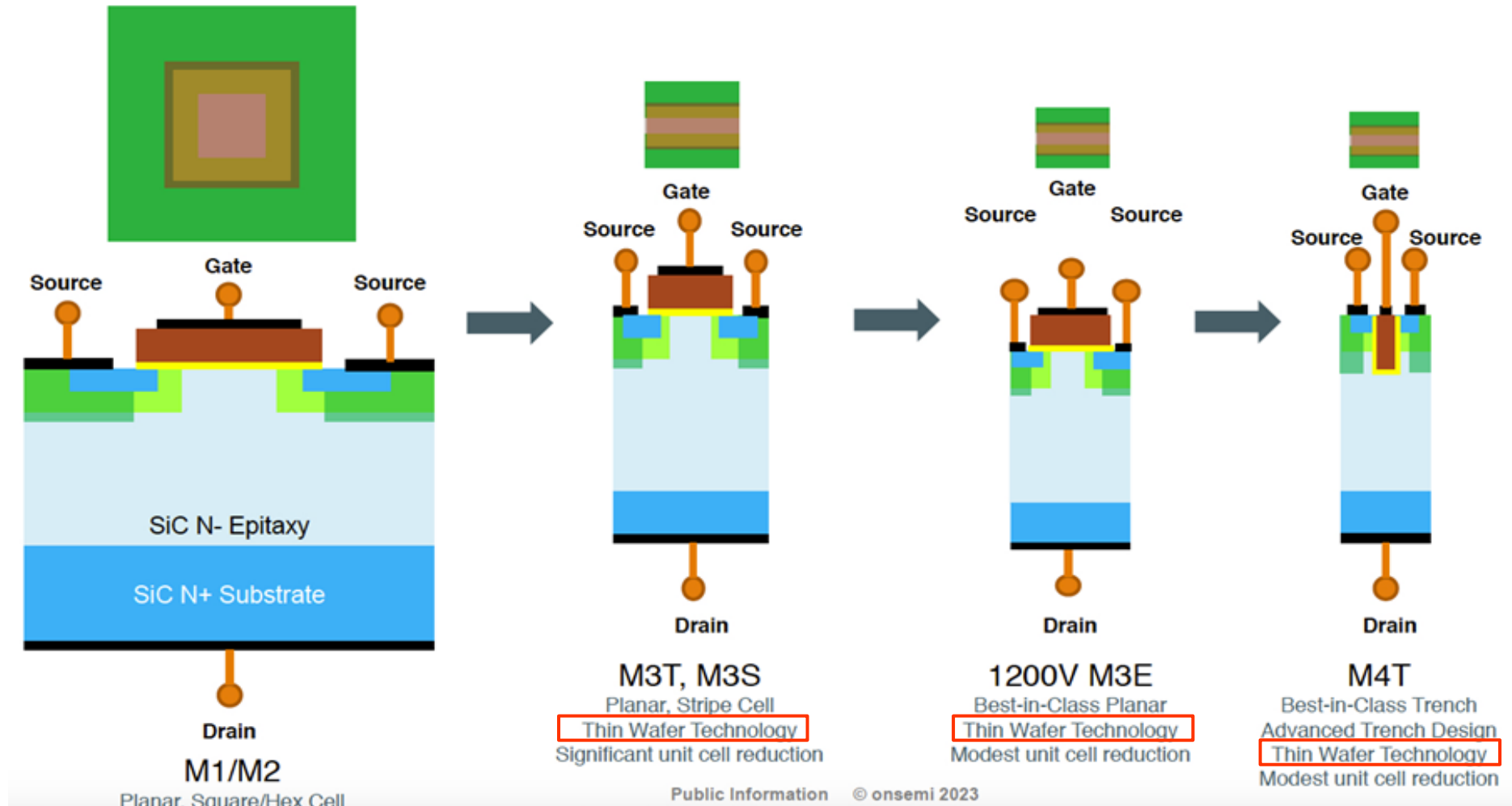
Next generation focus on SiC and 12"

AI Require More Efficient Thermal Solution



Source: E.Sun Security, company data, PSI

Power Discrete Must Do Thin Wafer Process

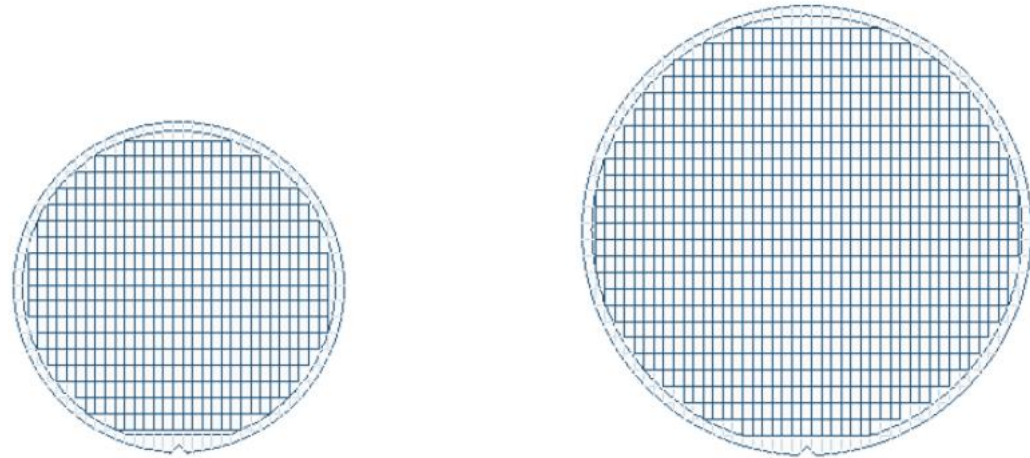


Source: M. Das, "Market Dynamics of the Automotive SiC Revolution for Electrification," PowerUP Expo 2023



Advantage Of Large Diameter SiC Wafer

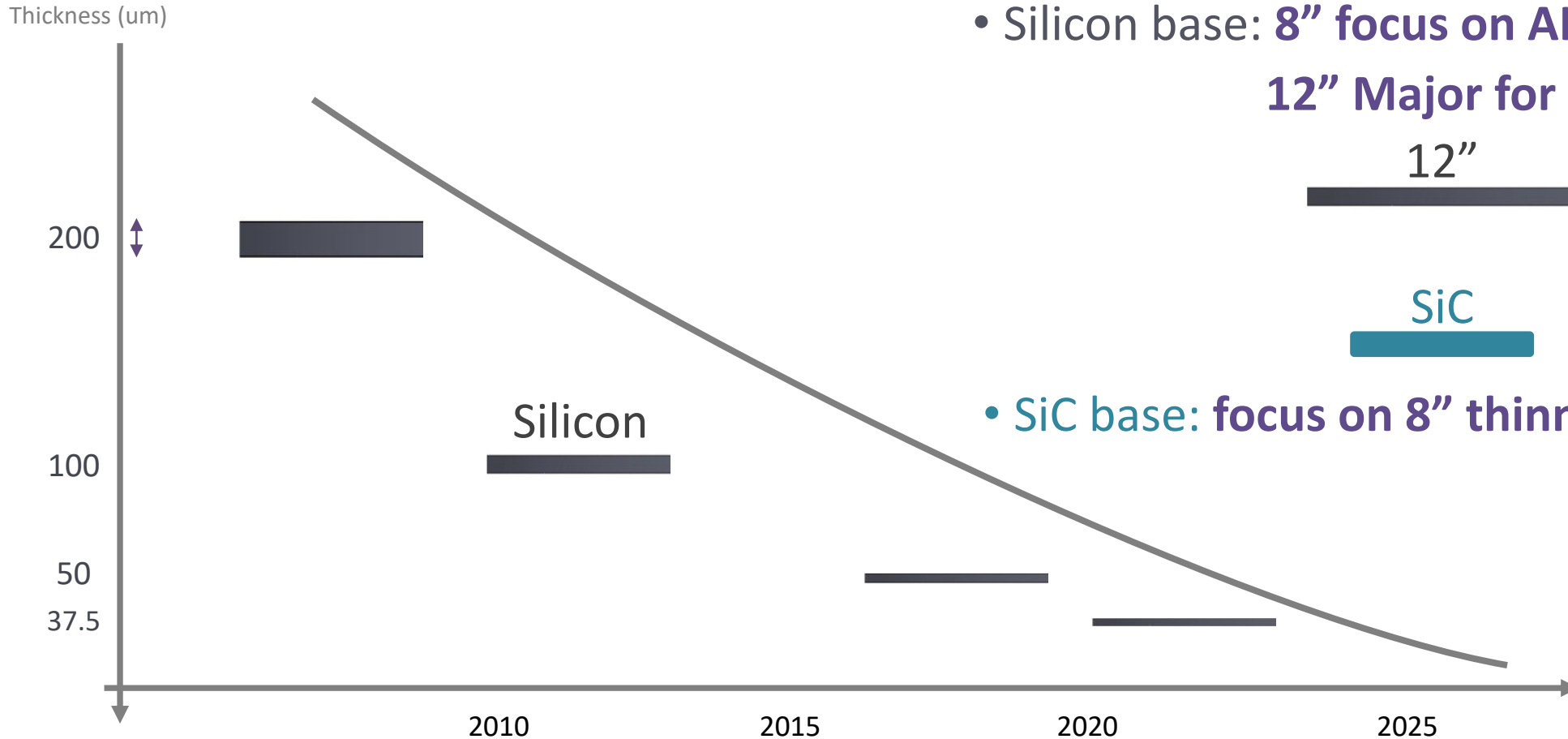
32 mm² die



	150mm	200mm
# whole die	448	845
% edge die	14	7

More devices from a single wafer with enhanced productivity and efficiency

Thinning Bu Roadmap

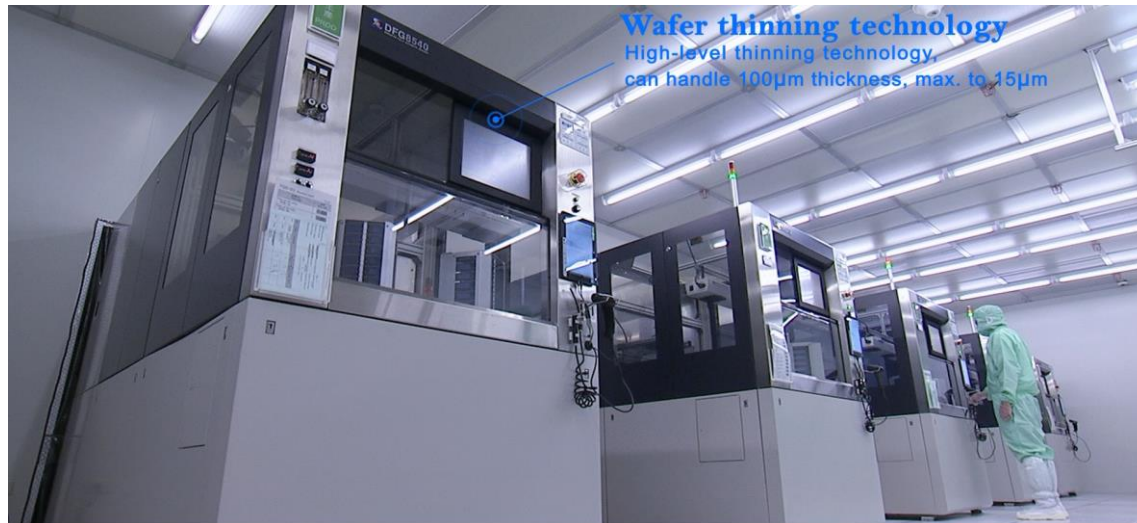


- Silicon base: **8"** focus on AI sever
12" Major for Adv. packaging

- SiC base: **focus on 8"** thinning

WW No.1 Thinning House **Capacity**

FSM → BGBM → Test



Key Takeaways

Key Takeaways

- The global semiconductor industry is poised to become a trillion-dollar industry by 2030. Major growth is **driven by AI and Smart electric vehicles.**
- For PSI, 2024 marks a transitional year, heralding significant growth leading into 2025. The year **2025 is poised to witness substantial growth.**
- LT: Reclaim, overseas 12" factories increasing, PSI **planning overseas expansion.**
Thinning, the demand for EV Surging, and the **8" SiC thinning process is enabling.**
- ST: Reclaim expects higher recovery in 2H. **Taichung Fab capacity pull in.**
Thinning high inventory in major customers, except AI. **Focus on AI customers.**

Thank you
